

SOT1429-1

plastic, heatsink small outline package; 6 leads(flat)

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HSOP6F
Package type industry code	HSOP6F
Package style descriptive code	HSOP (heatsink small outline package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-10-2014

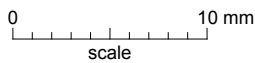
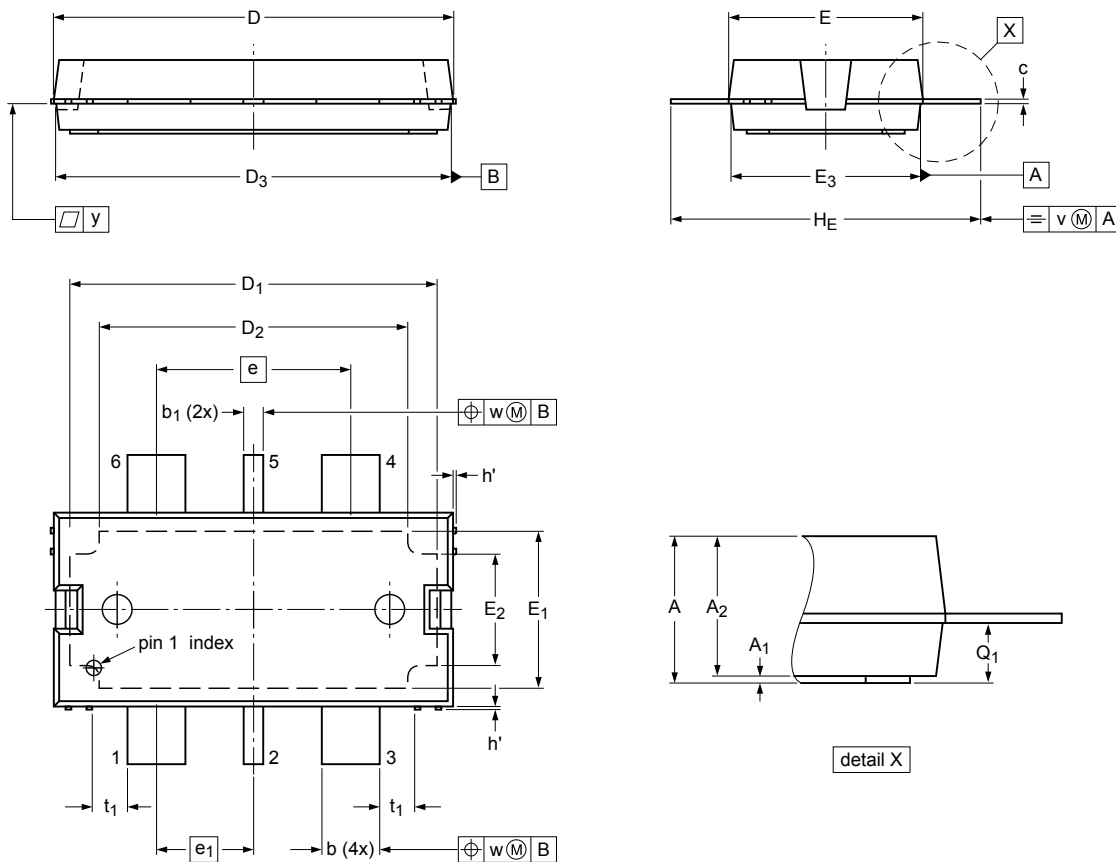
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	20.52	-	20.57	20.62	mm
E	package width	9.91	-	9.96	10.01	mm
A	seated height	-	-	-	3.9	mm
e	nominal pitch	-	-	10	-	mm
n ₂	actual quantity of termination	-	-	6	-	



2. Package outline

HSOP6F: plastic, heatsink small outline package; 6 leads(flat) SOT1429-1



Dimensions (mm are the original dimensions)

Unit	A	A ₁	A ₂	b	b ₁	c	D ⁽¹⁾	D ₁	D ₂	D ₃	E ⁽¹⁾	E ₁	E ₂	E ₃	e	e ₁	H _E	h'	t ₁	Q ₁	v	w	y	
max	3.9	0.2	3.65	3.05	1.05	0.27	20.62	19.00	16.05	20.44	10.01	8.18	5.89	9.83			16.16	0.25		1.62				
mm nom		0.1	3.60	3.00	1.00	0.22	20.57	18.95	16.00	20.39	9.96	8.13	5.84	9.78	10.0	5.0	15.96		1.8	1.57	0.25	0.25	0.1	
min		0.0	3.55	2.95	0.95	0.17	20.52	18.90	15.95	20.34	9.91	8.08	5.79	9.73			15.76			1.52				

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

so1429-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1429-1					14-10-06-14-10-30

Fig. 1. Package outline HSOP6F (SOT1429-1)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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